ABSTRACT

The present disclosure provides a substrate processing apparatus and a protective layer forming method that can protect surfaces of metal regions after a polishing process from oxidation and adhesion of cutting chips and particles caused in a process after polishing. The substrate processing apparatus according to the present disclosure includes a polishing device for polishing a semiconductor substrate, a protective layer forming device for forming a protective layer on a surface of the substrate using a silane coupling agent or a resin protective film agent, and a control device. The control device controls the polishing device and the protective layer forming device such that the protective layer forming device forms the protective layer on the substrate after the polishing device finishes polishing the substrate.

Fig. 1